



General Description

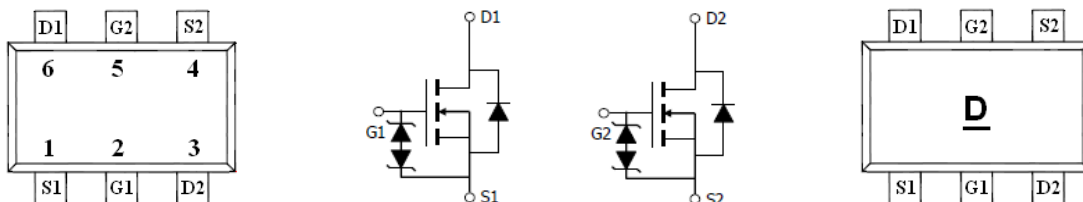
AFN1026S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- 60V/0.5A , $R_{DS(ON)}=2400m\Omega@V_{GS}=10V$
- 60V/0.2A , $R_{DS(ON)}=3000m\Omega@V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- ESD Protection (>2KV) Diode design-in
- SOT-563 package design

Pin Description (SOT-563)



Application

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Smart Phones, Paggers

Pin Define

Pin	Symbol	Description
1	S1	Source 1
2	G1	Gate 1
3	D2	Drain 2
4	S2	Source 2
5	G2	Gate 2
6	D1	Drain1

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN1026SS56RG	<u>D</u>	SOT-563	Tape & Reel	3000 EA

※ AFN1026SS56RG : 7" Tape & Reel ; Pb- Free ; Halogen -Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	I _D	T _A =25°C	0.35
		T _A =70°C	0.23
Pulsed Drain Current	I _{DM}	0.65	A
Continuous Source Current(Diode Conduction)	I _S	0.25	A
Power Dissipation	P _D	T _A =25°C	0.25
		T _A =70°C	0.15
Operating Junction Temperature	T _J	-55/150	°C
Storage Temperature Range	T _{STG}	-55/150	°C

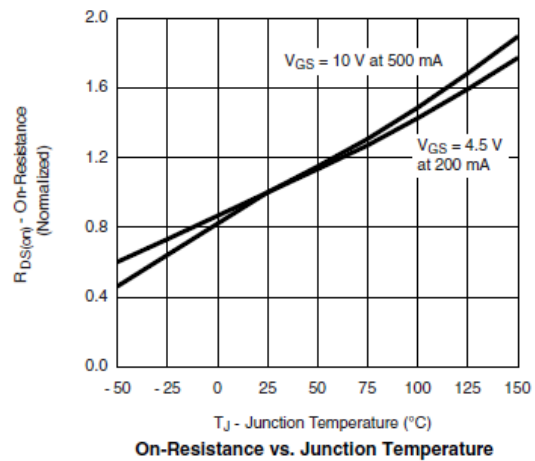
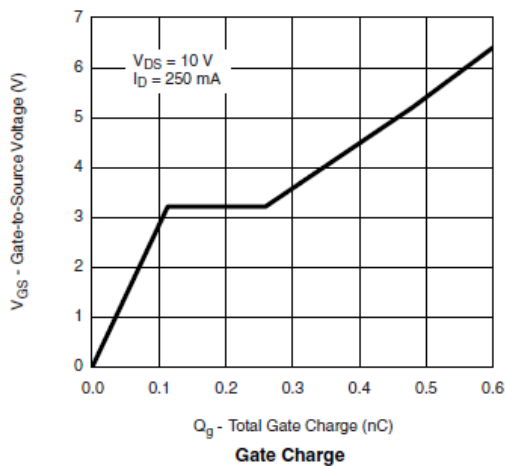
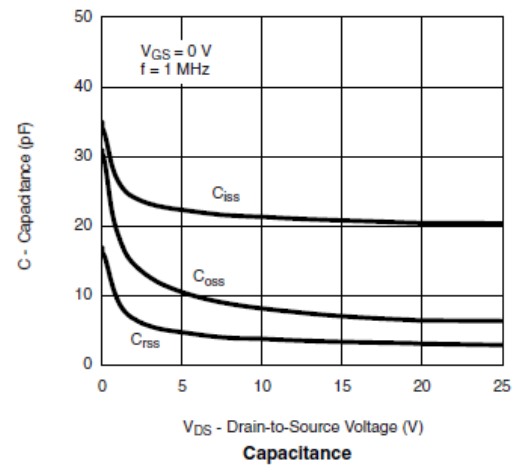
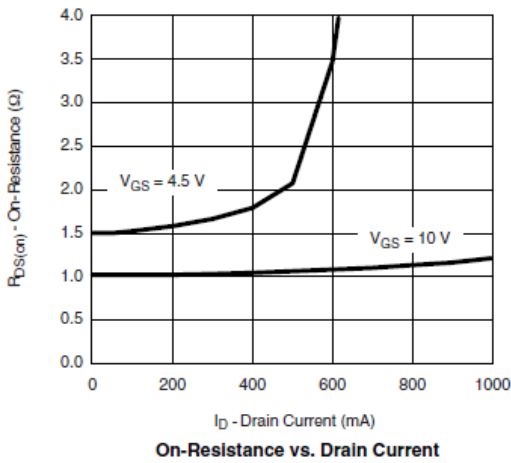
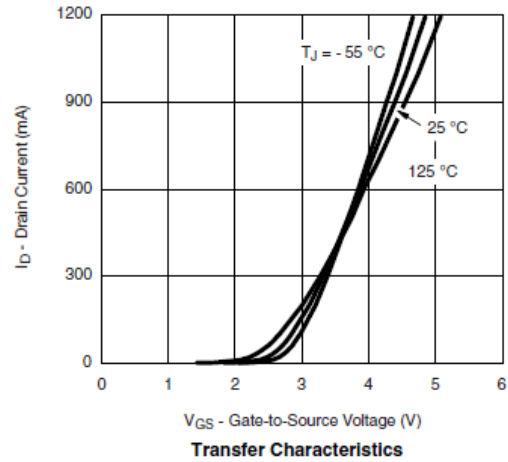
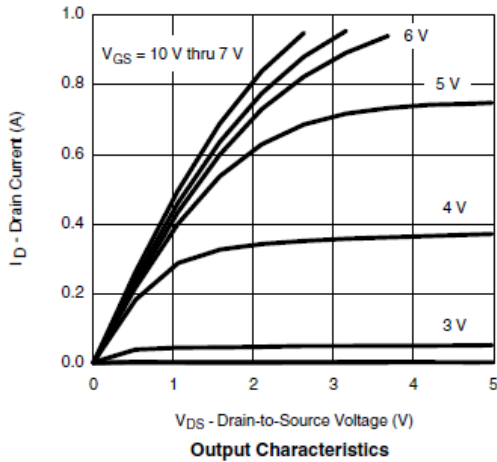
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0		2.0	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			3	uA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	uA
		V _{DS} =60V, V _{GS} =0V T _J =85°C			10	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =0.5A		1200	2400	mΩ
		V _{GS} = 4.5V, I _D =0.2A		1700	3000	
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =0.2A		0.2		S
Diode Forward Voltage	V _{SD}	I _S =0.2A, V _{GS} =0V		0.75	1.4	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =10V, V _{GS} =4.5V I _D ≅0.25A		450		pC
Gate-Source Charge	Q _{gs}			110		
Gate-Drain Charge	Q _{gd}			150		
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V f=1MHz		30		pF
Output Capacitance	C _{oss}			8		
Reverse Transfer Capacitance	C _{rss}			5		
Turn-On Time	t _{d(on)}	V _{DD} =30V, R _L =150Ω I _D ≅0.2A, V _{GEN} =10V R _G =10Ω		4	10	ns
	t _r			5	15	
Turn-Off Time	t _{d(off)}			12	20	
	t _f			10	20	

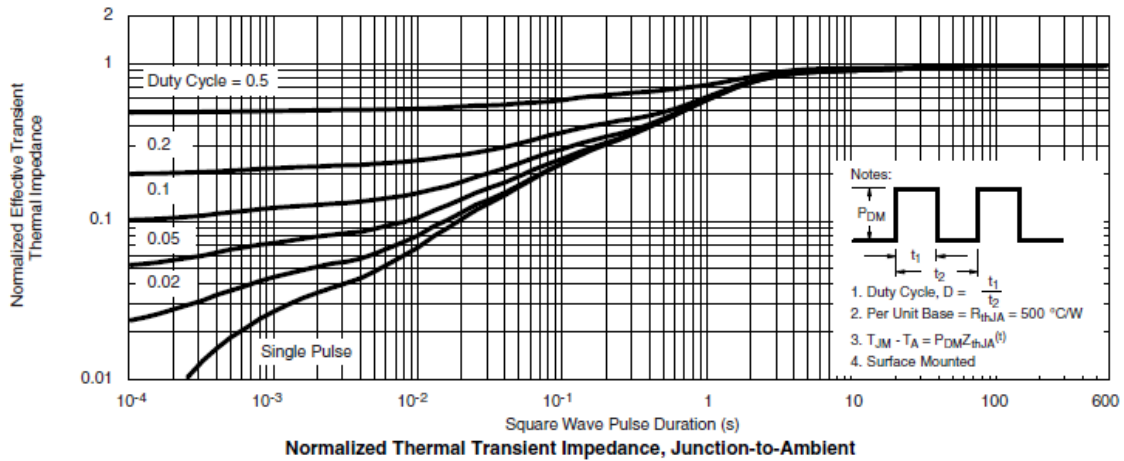
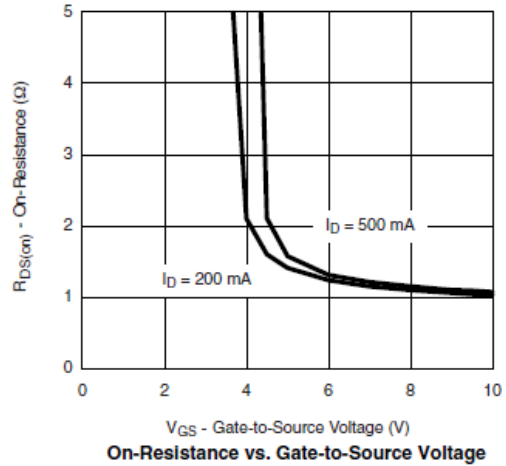
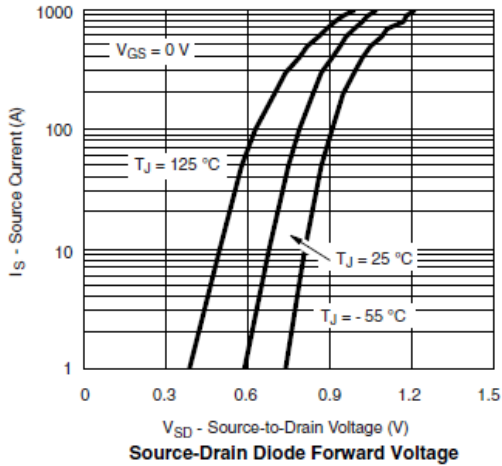


Typical Characteristics





Typical Characteristics





Typical Characteristics

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

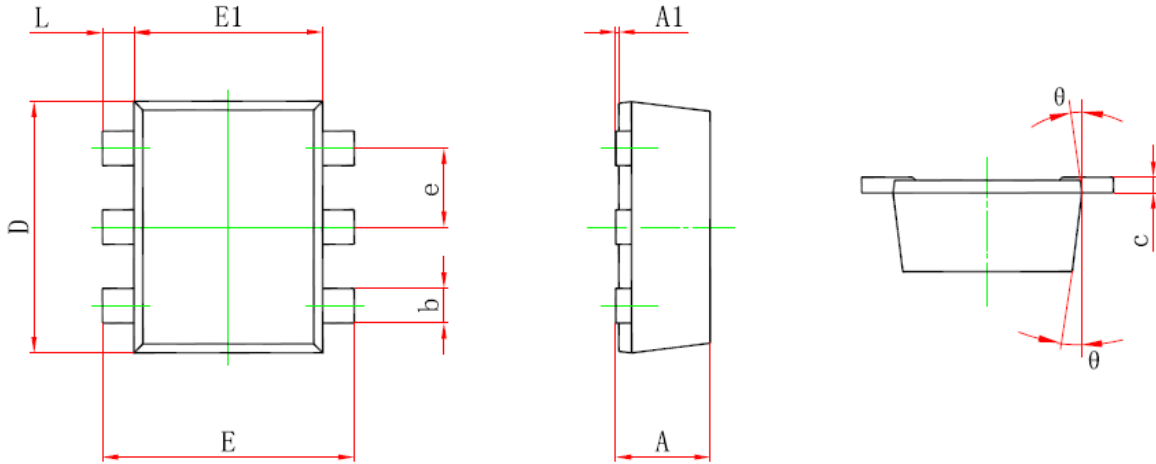


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (SOT-563)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.525	0.600	0.021	0.024
A1	0.000	0.050	0.000	0.002
e	0.450	0.550	0.018	0.022
c	0.090	0.160	0.004	0.006
D	1.500	1.700	0.059	0.067
b	0.170	0.270	0.007	0.011
E1	1.100	1.300	0.043	0.051
E	1.500	1.700	0.059	0.067
L	0.100	0.300	0.004	0.012
θ	7° REF.		7° REF.	

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